IN THE SPECIFICATION

Correct the paragraph beginning at page 3, line 33 as follows:

Fig. 3A is an expanded cross-sectional view of the electronic component feeding apparatus of the first embodiment of this invention, and FIG. 3B is a plan view of a high speed electronic component mounting instrument including the electronic component feeding apparatus.

A1

Correct the paragraph beginning at page 4, line 20 as follows:

Fig. 1 is a side view of a high-speed electronic component mounting instrument 1, and Fig. 2 is a perspective external view of the feeding constituent of the mounting instrument. As seen from both figures, the high-speed electronic component mounting instrument consists of an apparatus main body 2, a feeding portion 3 for feeding electronic components A, and a mounting portion 4 for mounting electronic components A to print board B, in such a way that the feeding portion 3 and the mounting portion 4 are aligned parallel along the main body 2, having the main body 2 in between. The feeding portion 3 includes an apparatus for feeding electronic components as shown in the figures.

A2

Correct the paragraph beginning at page 5, line 3 as follows:

A3

The feeding portion 3, which is basically the apparatus for feeding the electronic components, includes a slide platen 11 with its longitudinal direction being perpendicular to the plane of the figures (Fig. 1 and Fig. 3A), four slide bases (unit bases) 12 mounted on the slide platen 11 for sliding thereon, a plurality of tape cassettes (component feeding unit) 13 detachably mounted on the slide base 12, and a linear motor 14 placed between the slide platen 11 and each slide base 12.

Correct the paragraph beginning at page 5, line 9 as follows:

As shown in Fig. 2, among the four slide bases 12, one pair of the slide bases 12 rests at one end of the slide platen 11 and another pair rests at the other end. During the operation, the two pairs of the slide bases 12 with each slide base 12 carrying a group of tape cassettes 13 come to the main body 2 alternatively. While one pair with each slide base 12 carrying a group of tape cassettes 13 moves (slides) to the position of the main body 2 and rests there for component feeding operation, another pair is at the home position (one end of the slide platen) for changing the tape cassettes 13 in preparation for the next feeding operation. Fig. 2 schematically shows the pair of slide bases 12 without groups of tape cassettes 13 and the position of the main body 2 relative to the slide platen 11.

Correct the paragraph beginning at page 5, line 18 as follows:

As seen from and Fig. 3A, each tape cassette 13 is designed to be thin so that a group of the tape cassettes 13 can be mounted on the upper surface of the slide base 12 being laterally oriented (perpendicular to the longitudinal direction of the slide platen) with a narrow space among them. Each tape cassette 13 has its designated position on the upper surface of the slide base 12 and can easily be attached to or detached from the position by a simple lever operation. The mounting head 8 (suction nozzle 9) of the apparatus main body 2 comes to the opposite end of the tape cassette 13 mounted on the slide base 12 to the tape reel 16 for picking up the electronic component A. The tape cassette 13 has carrier tape C with electronic components A being contained therein at a predetermined pitch, which is wound to a tape reel 16. The electronic components A are picked up one by one by the suction nozzle 9 from the carrier tape C, which is unreeled from the tape reel 16. Fig. 3B is a schematic plan view of the high-speed electronic component mounting instrument 1 to show the position of the slide platen 11 relative to the main body 2.